

ALPHA[®] SACX[®] PLUS 0507, 0500

Lead-Free Wave Solder and Rework Alloy

DESCRIPTION

ALPHA SACX Plus 0507 is one of our very popular, SACX Plus alloy series. It is suitable for use as a replacement for SnPb, SAC305 and other low silver SAC alloys in wave solder, lead tinning and rework processes. **ALPHA SACX Plus 0507** is engineered to deliver the high level of soldering performance and reliability but it also exhibits minimal copper erosion when subjected to the long and hot exposure times common in selective soldering and rework processes.

The **ALPHA SACX Plus 0500** variant is used as a replenishment alloy in solder baths with elevated copper levels. As with all Alpha Metals bar solder, Alpha's proprietary Vaculoy manufacturing process is used to remove certain impurities, particularly oxides. The product is further enhanced with the addition of other materials designed to further reduce drossing, increase wetting speed and force and improve joint cosmetics.

READ ENTIRE TECHNICAL DATA SHEET BEFORE USING THIS PRODUCT

FEATURES & BENEFITS

- Lowers Total Cost of Ownership due to the lower material cost, high yields and low dross generation.
- Excellent mechanical reliability.
- Gives very good hole fill and drainage due to the lower surface tension attributed to Ag.
- Reduces erosion of copper plating during rework improving assembly reliability.
- Delivers good performance across a range of flux technologies.

The proprietary Vaculoy process is a highly effective method for removing included oxides from solder. This is extremely important because included oxides generate excessive drossing and increase the viscosity of the solder. Solder with higher viscosity can result in increased soldering defects (i.e., solder bridging).

APPLICATION GUIDELINES

ALPHA SACX Plus 0507 is suitable for wave soldering, lead tinning and reworking both through hole and surface mount components in a lead-free process. It is suited to single side and relatively complex, dual sided mixed technology boards. A solder pot temperature of 255 to 265 °C (491 to 509 °F) is recommended with a contact time 2.3 to 3.5 seconds. For suitable wave solder fluxes, contact your local sales representative. Lead-free Reclaim services including dedicated lead-free containers is also available, please consult your local Alpha sales office.

TECHNICAL SPECIFICATION

Complies with all requirements of RoHS Directive (Article 4.1 of the European Directive 2011/65/EU). Alloy specification for Maximum Lead (Pb) Content = 0.05%.

Material Property	Units	SACX Plus 0507
Solidus	Celsius	217
Liquidus	Celsius	228
Hardness (HV 2.5)	HV	13.0
Density	g/cc	7.40
Specific Heat Capacity	J/g K	0.23
Tensile Stress	MPa	32.7
Elongation at failure	%	21.8
Thermal Expansion Coefficient	@ 20 to 100 °C, $\mu\text{m}/\text{m } ^\circ\text{C}$	19.5
	@100 to 180 °C), $\mu\text{m}/\text{m } ^\circ\text{C}$	19.5
Silver Content	%	0.5 +0.15/-0.05
Copper Content	%	0.70 +/-0.1
Lead Content	%	Max 0.05%

RECOMMENDED WAVE SOLDER PROCESS SETTINGS

Wave Configuration	Process Parameter	Suggested Process Settings
Single Wave	Pot temperature	255 to 265 °C (491 to 509 °F)
	Conveyor speed	1.0 to 1.5 m/min (3.3 to 5 ft/min)
	Contact time	2.3 to 2.8 seconds
	Wave Height	1/2 to 2/3 of board thickness
	Dross removal	Once per 8 hour run time
	Copper Check	Every 8,000 boards until 40,000
Dual Wave	Pot temperature	255 to 265 °C (491 to 509 °F)
	Conveyor speed	1.0 to 1.5 m/min (3.3 to 5 ft/min)
	Contact time	3.0 to 3.5 seconds
	Wave Height	1/2 to 2/3 of board thickness
	Dross removal	Once per 8 hour run time
These are general guidelines which have proven to yield excellent results; however, depending upon your equipment, components, and circuit boards, your optimal settings may be different. To optimize your process, it is recommended to perform a design experiment, optimizing the most important variables (i.e., amount of flux applied, conveyor speed, topside preheat temperature, solder pot temperature and board orientation, etc...).		

MANAGEMENT OF COPPER LEVELS IN THE BATH

Management of the copper level in the wave solder bath is critical to ensure low defects in the soldering process. There is a tendency for the copper levels within a high tin bearing alloy wave solder bath to increase due to copper dissolution from the PCB. This effect increases based on the level of exposed copper on the assembly, as in the case of boards using OSP pad finishes.

It is recommended that the copper is controlled at between 0.7% and max 1.0% for ALPHA SACX Plus 0507 alloy. If the copper levels are higher than 1.0% then this will increase the liquidus temperature which in turn may mean that the solder bath temperature must be increased to maintain the process yields.

The copper levels in the bath can be controlled by means of adding ALPHA SACX Plus 0500 to the wave solder pot. It may be the case that equilibrium can be attained by continuing with ALPHA SACX Plus 0500 additions as the only means of solder top up, however each process is unique, and we would recommend regular analysis of the solder bath so that good control of copper can be maintained.

This analysis service is available from Alpha, contact your local sales office for details.

RECOMMENDED ACTIONS LEVELS FOR WAVE SOLDER IMPURITIES

Please find below a list of recommended action levels for wave solder bath impurities. For information of specific action plans to bring your solder bath back to an acceptable condition please contact your local sales office.

Element	ACTION Levels %	Notes
Sn	BAL	No Action level.
Pb	0.10	RoHS Directive 2011/65/EU states a maximum Lead content of 0.1%
As	0.03	Levels greater than 0.03% can cause de-wetting.
Cu	1.0	SACX Plus 0507 is tolerant to copper levels up to 1.0%, SACX Plus 0500 copper free should be added to maintain copper levels. Levels above 1.0% may cause more bridging.
Bi	0.20	Lead Free alloys are tolerant to Bi up to 1.0%, however if levels above 0.20% are detected this indicates some contamination issues that should be investigated
Zn	0.003	Levels greater than 0.003% may cause increased bridging and icicling, as well as increased crossing rates in the solder bath.
Fe	0.02	Greater than 0.02% Iron can be an indicator of pot erosion and may cause gritty joints and the formation of FeSn ₂ IMC needles that can cause bridging.
Ag	1.0	Silver levels of 4% are used in some SAC alloys, however if the levels in SACX 0507 rise above 1% then some investigations should be held to establish the cause.
Sb	0.20	Lead Free alloys are tolerant to Sb up to 1.0%, however if levels above 0.20% are detected this indicates some contamination issues that should be investigated
Ni	0.05	Levels greater than 0.05% may start to slow wetting and may reduce hole fill. Evaluate soldering performance if levels exceed 0.05%. Locate and eliminate source of high Ni levels.
Cd	0.003	RoHS Directive 2011/65/EU states a maximum Cadmium content of 0.01%. Levels of 0.003% may cause higher level of bridging and icicling.
Al	0.002	Levels greater than 0.002% may cause higher levels of bridging and icicling and a greater level of surface oxidation in the solder bath.

AVAILABILITY

ALPHA SACX Plus 0507 is available in 1kg (2.2lb) bar, chunks, feeder ingots and solid wire.

RECYCLING SERVICES

We provide safe and efficient recycling services to help companies meet their environmental and legislative requirements and at the same time, maximize the value of their waste streams. Our service collects solder dross, solder scrap, and various forms of solder paste waste. Please contact your local sales representative for recycling capabilities in your area or [link here](#).



SAFETY & WARNING

It is recommended that the company/operator read and review the Safety Data Sheets for the appropriate health and safety warnings before use. **Safety Data Sheets are available at MacdermidAlpha.com/assembly-solutions/knowledge-base.**

STORAGE

Store the solder bar in a cool, dry and non-corrosive environment. Wrap up the solder bar when not in use to reduce exposure to environment.

CONTACT INFORMATION

**To confirm this document is the most recent version, please contact
 Assembly@MacDermidAlpha.com
www.macdermidalpha.com**

<p>North America 109 Corporate Blvd. South Plainfield, NJ 07080, USA 1.800.367.5460</p>	<p>Europe Unit 2, Genesis Business Park Albert Drive Woking, Surrey, GU21 5RW, UK 44.01483.758400</p>	<p>Asia 8/F., Paul Y. Centre 51 Hung To Road Kwun Tong, Kowloon, Hong Kong 852.3190.3100</p>
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Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE. Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588

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